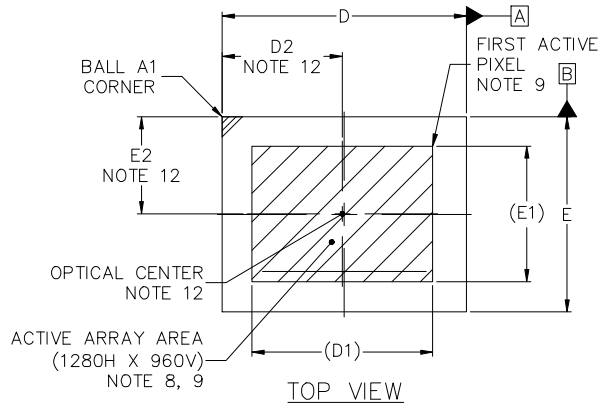


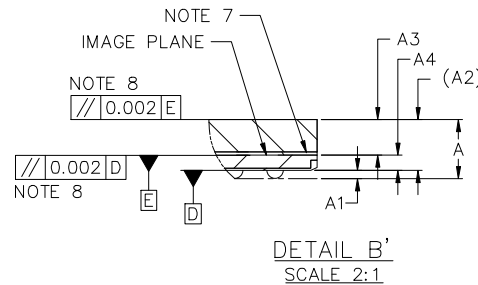
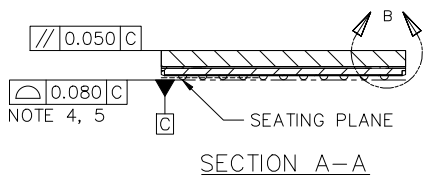
ODCSP87 6.05x4.83x0.63, 0.50P
CASE 570AZ
ISSUE A

DATE 17 JUN 2024

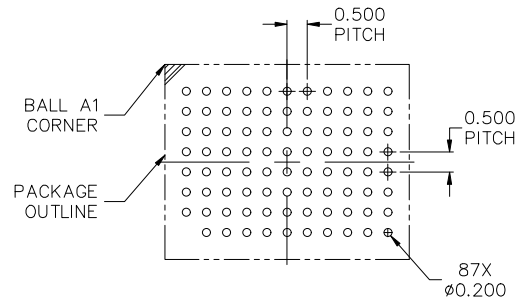
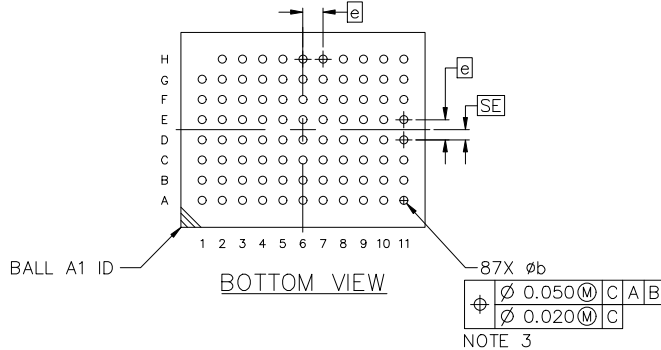


NOTES:

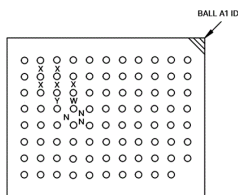
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 0.1^\circ$.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.046, 0.012).



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.762
A1	0.081	0.101	0.121
A2	0.631 REF.		
A3	0.425	0.440	0.455
A4	0.171	0.191	0.211
b	0.184	0.204	0.224
D	6.030	6.055	6.080
D1	4.480 REF.		
D2	2.956	2.981	3.006
E	4.810	4.835	4.860
E1	3.360 REF.		
E2	2.380	2.405	2.430
e	0.500 BSC		



GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
W = Work Week
NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	ODCSP87 6.05x4.83x0.63, 0.50P	PAGE 1 OF 1

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